

Low Skew, 1-to-4 Differential-to-3.3V LVPECL Fanout Buffer

DATA SHEET

GENERAL DESCRIPTION

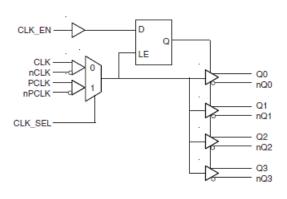
The 8533I-01 is a low skew, high performance 1-to-4 Differential-to-3.3V LVPECL Fanout Buffer. The 8533I-01 has two selectable clock inputs. The CLK, nCLK pair can accept most standard differential input levels. The PCLK, nPCLK pair can accept LVPECL, CML, or SSTL input levels. The clock enable is internally synchronized to eliminate runt pulses on the outputs during asynchronous assertion/deassertion of the clock enable pin.

Guaranteed output and part-to-part skew characteristics make the 8533I-01 ideal for those applications demanding well defined performance and repeatability.

FEATURES

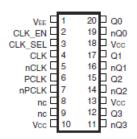
- Four differential 3.3V LVPECL outputs
- Selectable differential CLK, nCLK or LVPECL clock inputs
- . CLK, nCLK pair can accept the following differential input levels: LVDS, LVPECL, LVHSTL, SSTL, HCSL
- PCLK, nPCLK supports the following input types: LVPECL, CML, SSTL
- Maximum output frequency: 650MHz
- Translates any single-ended input signal to 3.3V LVPECL levels with resistor bias on nCLK input
- Output skew: 30ps (maximum)
- Part-to-part skew: 150ps (maximum)
- Propagation delay: 1.5ns (maximum), CLK/nCLK
- Additive phase jitter, RMS: 0.060ps (typical)
- 3.3V operating supply
- -40°C to 85°C ambient operating temperature
- · Available in lead-free (RoHS 6) package

BLOCK DIAGRAM



PIN ASSIGNMENT

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8533I-01 20-Lead TSSOP 6.5mm x 4.4mm x 0.92mm package body G Package Top View



TABLE 1. PIN DESCRIPTIONS

Number	Name	Ty	/ре	Description
1	V _{EE}	Power		Negative supply pin.
2	CLK_EN	Input	Pullup	Synchronizing clock enable. When HIGH, clock outputs follow clock input. When LOW, Q outputs are forced low, nQ outputs are forced high. LVC-MOS / LVTTL interface levels.
3	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects differential PCLK, nPCLK inputs. When LOW, selects CLK, nCLK inputs. LVCMOS / LVTTL interface levels.
4	CLK	Input	Pulldown	Non-inverting differential clock input.
5	nCLK	Input	Pullup	Inverting differential clock input.
6	PCLK	Input	Pulldown	Non-inverting differential LVPECL clock input.
7	nPCLK	Input	Pullup	Inverting differential LVPECL clock input.
8, 9	nc	Unused		No connect.
10, 13, 18	V _{cc}	Power		Positive supply pins.
11, 12	nQ3, Q3	Output		Differential output pair. LVPECL interface levels.
14, 15	nQ2, Q2	Output		Differential output pair. LVPECL interface levels.
16, 17	nQ1, Q1	Output		Differential output pair. LVPECL interface levels.
19, 20	nQ0, Q0	Output		Differential output pair. LVPECL interface levels.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLUP}	Input Pullup Resistor			51		kΩ
R _{PULLDOWN}	Input Pulldown Resistor			51		kΩ



TABLE 3A. CONTROL INPUT FUNCTION TABLE

	Inputs	Out	outs	
CLK_EN	CLK_SEL	Selected Source	Q0:Q3	nQ0:nQ3
0	0	CLK, nCLK	Disabled; LOW	Disabled; HIGH
0	1	PCLK, nPCLK	Disabled; LOW	Disabled; HIGH
1	0	CLK, nCLK	Enabled	Enabled
1	1	PCLK, nPCLK	Enabled	Enabled

After CLK_EN switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as shown in Figure 1. In the active mode, the state of the outputs are a function of the CLK, nCLK and PCLK, nPCLK inputs as described in Table 3B.

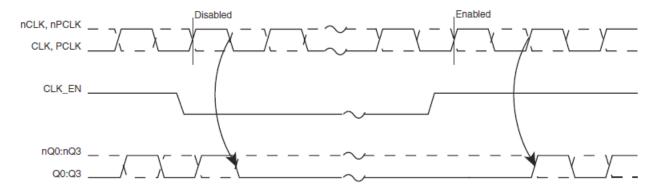


FIGURE 1. CLK_EN TIMING DIAGRAM

TABLE 3B. CLOCK INPUT FUNCTION TABLE

In	puts	Out	puts	Input to Output Mode	Polarity
CLK or PCLK	nCLK or nPCLK	Q0:Q3	nQ0:nQ3	- Input to Output Mode Polanty	
0	1	LOW	HIGH	Differential to Differential	Non Inverting
1	0	HIGH	LOW	Differential to Differential	Non Inverting
0	Biased; NOTE 1	LOW	HIGH	Single Ended to Differential	Non Inverting
1	Biased; NOTE 1	HIGH	LOW	Single Ended to Differential	Non Inverting
Biased; NOTE 1	0	HIGH	LOW	Single Ended to Differential	Inverting
Biased; NOTE 1	1	LOW	HIGH	Single Ended to Differential	Inverting

NOTE 1: Please refer to the Application Information section, "Wiring the Differential Input to Accept Single Ended Levels".



ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{CC} 4.6V

Inputs, $V_{\rm I}$ -0.5V to $V_{\rm CC}$ + 0.5V

Outputs, $I_{\rm O}$

Continuous Current 50mA Surge Current 100mA

Package Thermal Impedance, θ_{JA} 73.2°C/W (0 Ifpm) Storage Temperature, T_{STG} -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics, $V_{cc} = 3.3V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{cc}	Positive Supply Voltage		3.135	3.3	3.465	V
I _{EE}	Power Supply Current				52	mA

Table 4B. LVCMOS / LVTTL DC Characteristics, $V_{cc} = 3.3V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V _{IH}	Input High Voltage			2		V _{cc} + 0.3	V
V _{IL}	Input Low Voltage			-0.3		0.8	V
	Input High Current	CLK_EN	$V_{IN} = V_{CC} = 3.465V$			5	μΑ
' ін	Imput riigir Current	CLK_SEL	$V_{IN} = V_{CC} = 3.465V$			150	μΑ
	I Innut I ou Current		$V_{IN} = 0V, V_{CC} = 3.465V$	-150			μΑ
' _{IL}	Input Low Current	CLK_SEL	$V_{IN} = 0V, V_{CC} = 3.465V$	-5			μΑ

Table 4C. Differential DC Characteristics, $V_{cc} = 3.3V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	r		$V_{CC} = V_{IN} = 3.465V$			5	μΑ
 ' ⊪	Input High Current	CLK	$V_{CC} = V_{IN} = 3.465V$			150	μΑ
	I Innest Laur Commant		$V_{CC} = 3.465V, V_{IN} = 0V$	-150			μΑ
'	Input Low Current	CLK	$V_{CC} = 3.465V, V_{IN} = 0V$	-5			μΑ
V _{PP}	Peak-to-Peak Input Voltage			0.15		1.3	V
V _{CMR}	Common Mode Inpu NOTE 1, 2	ut Voltage;		V _{EE} + 0.5		V _{CC} - 0.85	V

NOTE 1: For single ended applications, the maximum input voltage for CLK and nCLK is $V_{\rm cc}$ + 0.3V.

NOTE 2: Common mode voltage is defined as $V_{\rm IH}$.



Table 4D. LVPECL DC Characteristics, $V_{CC} = 3.3V \pm 5\%$, Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	Input High Current	PCLK	$V_{CC} = V_{IN} = 3.465V$			150	μA
'ін	Imput riigii Cuiteiit	nPCLK	$V_{CC} = V_{IN} = 3.465V$			5	μA
	Input Low Current	PCLK	$V_{CC} = 3.465 \text{V}, V_{IN} = 0 \text{V}$	-5			μA
'⊩	Input Low Current	nPCLK	$V_{CC} = 3.465 \text{V}, V_{IN} = 0 \text{V}$	-150			μΑ
V _{PP}	Peak-to-Peak Input	Voltage		0.3		1	V
V_{CMR}	Common Mode Inpu	ut Voltage; NOTE 1, 2		V _{EE} + 1.5		V _{cc}	V
V _{OH}	Output High Voltage; NOTE 3			V _{cc} - 1.4		V _{cc} - 0.9	V
V _{OL}	Output Low Voltage; NOTE 3			V _{cc} - 2.0		V _{cc} - 1.7	V
V _{SWING}	Peak-to-Peak Outpu	ıt Voltage Swing		0.6		1.0	V

NOTE 1: Common mode voltage is defined as V_{III}.

NOTE 2: For single ended applications the maximum input voltage for PCLK and nPCLK is V_{cc} + 0.3V.

NOTE 3: Outputs terminated with 50 $\!\Omega$ to V $_{\rm cc}$ - 2V.

Table 5. AC Characteristics, $V_{CC} = 3.3V \pm 5\%$, $TA = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency					650	MHz
	Propagation Delay; CLK, nCLK			1.15		1.5	ns
t _{PD}	NOTE 1	PCLK, nPCLK		1.0		1.3	ns
tsk(o)	Output Skew; NOTE 2, 4					30	ps
tsk(pp)	Part-to-Part Skew; N	IOTE 3, 4				150	ps
tjit	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter section				0.060		ps
t _R /t _F	Output Rise/Fall Time			300		800	ps
odc	Output Duty Cycle			47		53	%

All parameters measured at f £ 650MHz unless noted otherwise.

The cycle to cycle jitter on the input will equal the jitter on the output. The part does not add jitter.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

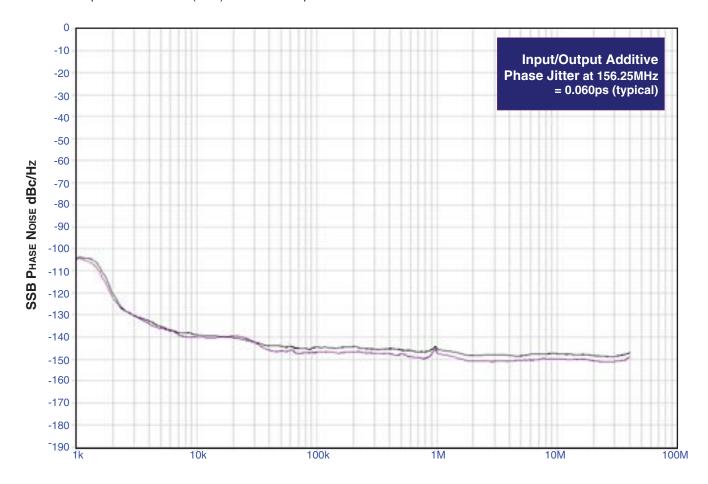
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.



ADDITIVE PHASE JITTER

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the *dBc Phase Noise*. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in

the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a *dBc* value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



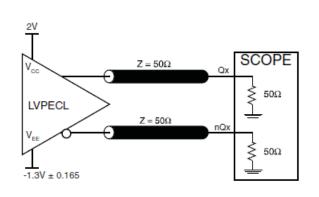
OFFSET FROM CARRIER FREQUENCY (Hz)

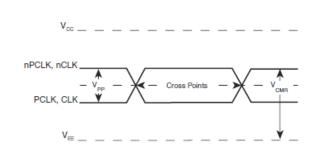
As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The

device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependent on the input source and measurement equipment.



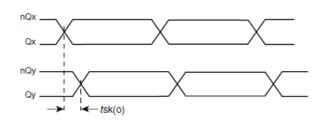
PARAMETER MEASUREMENT INFORMATION

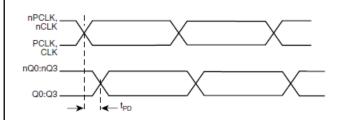




3.3V OUTPUT LOAD AC TEST CIRCUIT

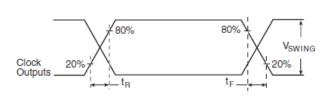
DIFFERENTIAL INPUT LEVEL

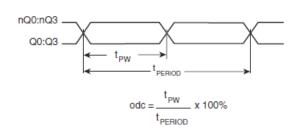




OUTPUT SKEW

PROPAGATION DELAY





OUTPUT RISE/FALL TIME

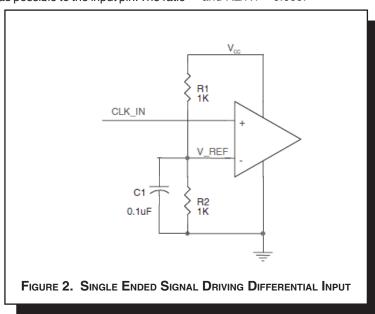


APPLICATION INFORMATION

WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 2 shows how the differential input can be wired to accept single ended levels. The reference voltage $V_REF = V_{cc}/2$ is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and V $_{\rm CC}$ = 3.3V, V_REF should be 1.25V and R2/R1 = 0.609.



RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

INPUTS: OUTPUTS:

CLK/nCLK INPUT:

For applications not requiring the use of the differential input, both CLK and nCLK can be left floating. Though not required, but for additional protection, a $1k\Omega$ resistor can be tied from CLK to ground.

PCLK/nPCLK INPUT:

For applications not requiring the use of a differential input, both the PCLK and nPCLK pins can be left floating. Though not required, but for additional protection, a $1k\Omega$ resistor can be tied from PCLK to ground.

LVCMOS CONTROL PINS:

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A $1k\Omega$ resistor can be used.

LVPECL OUTPUT

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All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.



DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both Vswing and Voh must meet the VPP and VcmR input requirements. Figures 3A to 3E show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the

vendor of the driver component to confirm the driver termination requirements. For example in *Figure 3A*, the input termination applies for ICS HiPerClockS LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

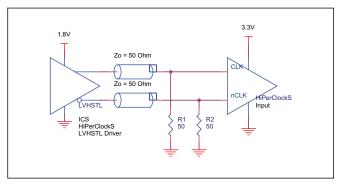


FIGURE 3A. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY ICS HIPERCLOCKS LVHSTL DRIVER

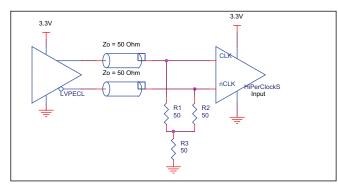


FIGURE 3B. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

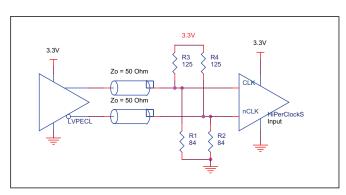


FIGURE 3C. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

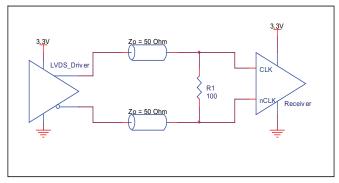


FIGURE 3D. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY 3.3V LVDS DRIVER

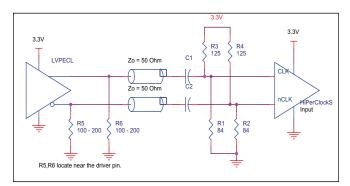


FIGURE 3E. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER WITH AC COUPLE



LVPECL CLOCK INPUT INTERFACE

The PCLK /nPCLK accepts LVPECL, CML, SSTL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. *Figures 4A to 4F* show interface examples for the HiPerClockS PCLK/nPCLK input driven by the most common driver types. The input interfaces suggested here are examples

only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.

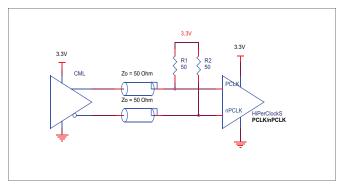


FIGURE 4A. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN
BY AN OPEN COLLECTOR CML DRIVER

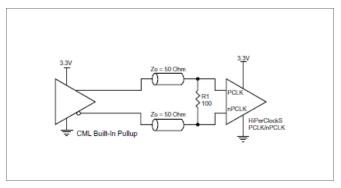


FIGURE 4B. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN BY A BUILT-IN PULLUP CML DRIVER

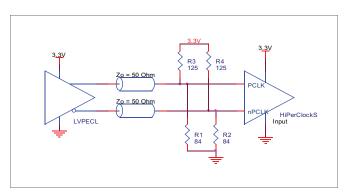


FIGURE 4C. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER

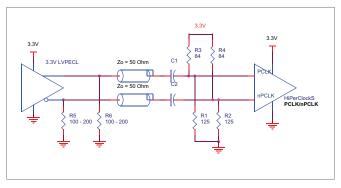


FIGURE 4D. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER WITH AC COUPLE

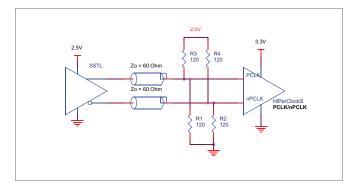


FIGURE 4E. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN BY AN SSTL DRIVER

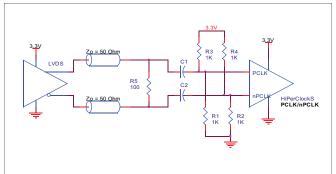


FIGURE 4F. HIPERCLOCKS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVDS DRIVER



TERMINATION FOR LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω transmission lines. Matched impedance

techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 5A and 5B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

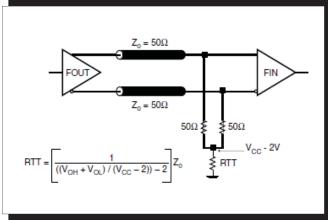


FIGURE 5A. LVPECL OUTPUT TERMINATION

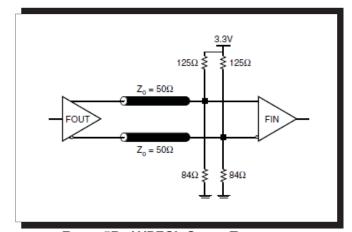


FIGURE 5B. LVPECL OUTPUT TERMINATION



POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the 8533I-01. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the 8533I-01 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{CC} = 3.3V + 5\% = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = V_{CC MAX} * I_{EE MAX} = 3.465V * 52mA = 180.2mW
- Power (outputs)_{MAX} = 30mW/Loaded Output pair
 If all outputs are loaded, the total power is 4 * 30mW = 120mW

Total Power _{MAX} (3.465V, with all outputs switching) = 180.2mW + 120mW = 300.2mW

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for Tj is as follows: Tj = θ_{JA} * Pd_total + TA

Tj = Junction Temperature

 $\theta_{JA} = Junction-to-Ambient Thermal Resistance$

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θJA must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 66.6°C/W per Table 6 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:

 $85^{\circ}\text{C} + 0.300\text{W} * 66.6^{\circ}\text{C/W} = 105^{\circ}\text{C}$. This is well below the limit of 125°C .

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

Table 6. Thermal Resistance θ_{JA} for 20-pin TSSOP, Forced Convection

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

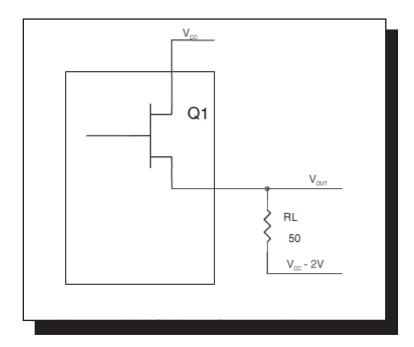
θJA by Velocity (Linear Feet per Minute)



3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in Figure 6.



To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of V_{cc} - 2V.

• For logic high,
$$V_{OUT} = V_{OH_MAX} = V_{CC_MAX} - 0.9V$$

$$(V_{CC MAX} - V_{OH MAX}) = 0.9V$$

• For logic low, $V_{OUT} = V_{OL_MAX} = V_{CC_MAX} - 1.7V$

$$(V_{CC_MAX} - V_{OL_MAX}) = 1.7V$$

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$Pd_{-}H = [(V_{OH_MAX} - (V_{CC_MAX} - 2V))/R_{L}] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - (V_{CC_MAX} - V_{OH_MAX}))/R_{L}] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - 0.9V)/50\Omega] * 0.9V = 19.8mW$$

$$Pd_{L} = [(V_{OL_MAX} - (V_{CC_MAX} - 2V))/R_{L}] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - (V_{CC_MAX} - V_{OL_MAX}))/R_{L}] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - 1.7V)/50\Omega] * 1.7V = 10.2mW$$

Total Power Dissipation per output pair = Pd_H + Pd_L = 30mW



RELIABILITY INFORMATION

Table 7. $\theta_{\text{JA}} \text{vs. Air Flow Table for 20 Lead TSSOP}$

θJA by Velocity (Linear Feet per Minute)

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for 8533I-01 is: 404



PACKAGE OUTLINE - G SUFFIX FOR 20 LEAD TSSOP

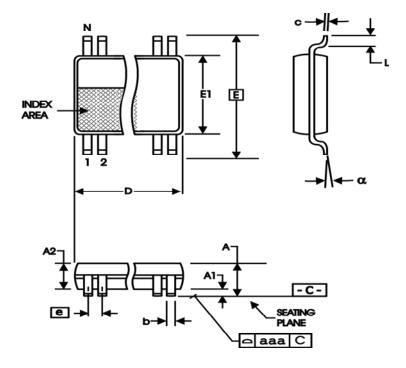


TABLE 8. PACKAGE DIMENSIONS

SYMBOL	Millimeters			
STWIDGE	Minimum	Maximum		
N	2	0		
А		1.20		
A1	0.05	0.15		
A2	0.80	1.05		
b	0.19	0.30		
С	0.09	0.20		
D	6.40	6.60		
E	6.40 E	BASIC		
E1	4.30	4.50		
е	0.65 E	BASIC		
L	0.45	0.75		
α	0°	8°		
aaa		0.10		

Reference Document: JEDEC Publication 95, MS-153



TABLE 9. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
8533AGI-01LF	8533AI01L	20 lead "Lead Free" TSSOP	tube	-40°C to 85°C
8533AGI-01LFT	8533AI01L	20 lead "Lead Free" TSSOP	tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.



	REVISION HISTORY SHEET					
Rev	Table	Page	Description of Change			
А	Т9	1 8 10 16	Features Section - added lead-free note. Added Recommendations for Unused Input and Output Pins. Updated LVPECL Clock Input Interface. Ordering Information Table - added lead-free part number, marking and note.	4/21/06		
Α	Т9	16	Ordering Information Table - Changed non lead free marking	12-6-07		
Α	Т9	16	Ordering Information Table - removed leaded devices. Updated data sheet format.	7/9/15		



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